

SiC JFET Division

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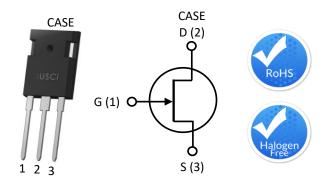
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Description

United Silicon Carbide, Inc offers the high-performance G3 SiC normally-on JFET transistors. This series exhibits ultra-low on resistance ($R_{DS(ON)}$) and gate charge (Q_G) allowing for low conduction and switching loss. The device normally-on characteristics with low $R_{DS(ON)}$ at V_{GS} = 0 V is also ideal for current protection circuits without the need for active control, as well as for cascode operation.



Part Number	Package	Marking
UJ3N120035K3S	TO-247-3L	UJ3N120035K3S

Features

- Typical on-resistance $R_{DS(on),typ}$ of $35m\Omega$
- Voltage controlled
- Maximum operating temperature of 175°C
- Extremely fast switching not dependent on temperature
- ◆ Low gate charge
- Low intrinsic capacitance
- RoHS compliant
- AECQ Qualified

Typical Applications

- Over current protection circuits
- DC-AC inverters
- Switch mode power supplies
- Power factor correction modules
- Motor drives
- Induction heating

Maximum Ratings

Parameter	Symbol	Test Conditions	Value	Units	
Drain-source voltage	V _{DS}		1200	V	
	V	DC	-20 to +3	V	
Gate-source voltage	V_{GS}	AC ⁽¹⁾	-20 to +20	V	
Continuous drain current (2)		T _C = 25°C	63	А	
	I _D	T _C = 100°C	46	А	
Pulsed drain current ⁽³⁾	I _{DM}	T _C = 25°C	185	А	
Power dissipation	P _{tot}	T _C =25°C	429	W	
Maximum junction temperature	$T_{J,max}$		175	°C	
Operating and storage temperature	T _J , T _{STG}		-55 to 175	°C	
Max. lead temperature for soldering, 1/8" from case for 5 seconds	T _L		250	°C	

- (1) +20V AC rating applies for turn-on pulses <200ns applied with external $R_G > 1\Omega$.
- (2) Limited by T_{J,max}
- (3) Pulse width t_p limited by T_{J,max}

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Electrical Characteristics (T_J = +25°C unless otherwise specified)

Typical Performance - Static

Darameter	Symbol	Test Conditions	Value			Units	
Parameter	Symbol Test Conditions		Min	Тур	Max	Units	
Drain-source breakdown voltage	BV _{DS}	V_{GS} = - 20V, I_D =1mA	1200			V	
Total drain leakage current	I _D	$V_{DS} = 1200V,$ $V_{GS} = -20V, T_{J} = 25^{\circ}C$		10	60	- μΑ	
		$V_{DS} = 1200V,$ $V_{GS} = -20V, T_{J} = 175^{\circ}C$		35			
Total gate leakage current	I _G	V _{GS} =-20V, T _j =25°C		12	100	μА	
		V _{GS} =-20V, T _j =175°C		50			
Drain-source on-resistance	R _{DS(on)}	$V_{GS}=2V, I_{D}=20A,$ $T_{J}=25^{\circ}C$		31		mΩ	
		V_{GS} =0V, I_D =20A, T_J = 25°C		35	45		
		$V_{GS}=2V, I_{D}=20A,$ $T_{J}=175^{\circ}C$		68			
		V_{GS} =0V, I_{D} =20A, T_{J} = 175°C		76			
Gate threshold voltage	V _{G(th)}	$V_{DS} = 5V, I_{D} = 70mA$	-14	-11.5	-6	V	
Gate resistance	R_{G}	f = 1MHz, open drain		2.4		Ω	

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Typical Performance - Dynamic

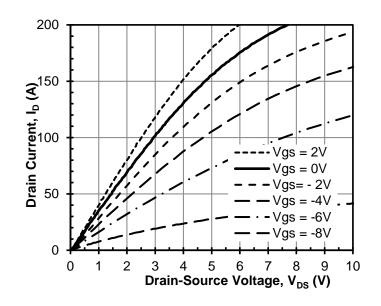
Parameter	symbol	Test Conditions	Value			Units		
Parameter	Syllibol	Test Conditions	Min	Тур	Max	Ullits		
Input capacitance	C _{iss}	V _{DS} = 100V,		2145				
Output capacitance	C _{oss}	V _{GS} = -20V,		180		pF		
Reverse transfer capacitance	C _{rss}	f = 100kHz		172				
Effective output capacitance, energy related	C _{oss(er)}	$V_{DS} = 0V \text{ to } 800V,$ $V_{GS} = -20V$		105		pF		
Total gate charge	Q_{G}	V 000V I 404		235				
Gate-drain charge	Q_{GD}	V_{DS} =800V, I_{D} = 40A, V_{GS} =-18V to 0V		130		nC		
Gate-source charge	Q_{GS}	V _{GS} 18V tO OV		25				
Turn-on delay time	t _{d(on)}	V _{DS} =800V, I _D =40A, Gate Driver =-18V to 0V,		25		ns		
Rise time	t _r			37				
Turn-off delay time	t _{d(off)}			48				
Fall time	t _f	$R_{G,EXT} = 1\Omega,$ Inductive Load,		39				
Turn-on energy	E _{ON}	FWD: UJ3D1220KSD T _J = 25°C		935		μͿ		
Turn-off energy	E _{OFF}			828				
Total switching energy	E _{TOTAL}			1763				
Turn-on delay time	t _{d(on)}			24		- ns		
Rise time	t _r	$V_{DS}=800V,\ I_{D}=40A,$ Gate Driver =-18V to 0V, $R_{G,EXT}=1\Omega,$ Inductive Load, $FWD:\ UJ3D1220KSD$ $T_{J}=150^{\circ}C$		35				
Turn-off delay time	t _{d(off)}			43				
Fall time	t _f			37				
Turn-on energy	E _{ON}			880				
Turn-off energy	E _{OFF}			800		μЈ		
Total switching energy	E _{TOTAL}			1680				

Thermal Characteristics

Parameter	symbol	Test Conditions	Value			Units
rarameter			Min	Тур	Max	Offics
Thermal resistance, junction-to-case	$R_{ heta$ JC			0.27	0.35	°C/W



Typical Performance Diagrams



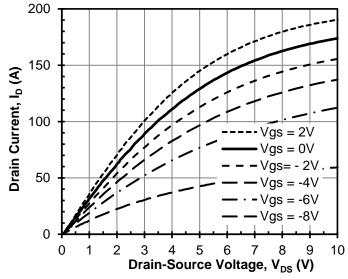
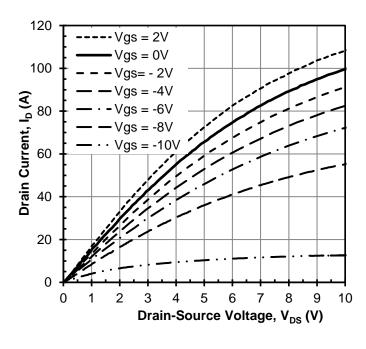
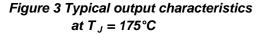


Figure 1 Typical output characteristics at $T_J = -55$ °C

Figure 2 Typical output characteristics at $T_J = 25$ °C





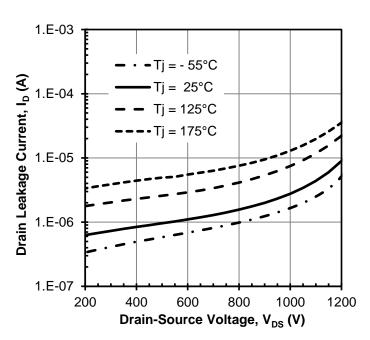


Figure 4 Typical drain-source leakage at $V_{GS} = -20V$

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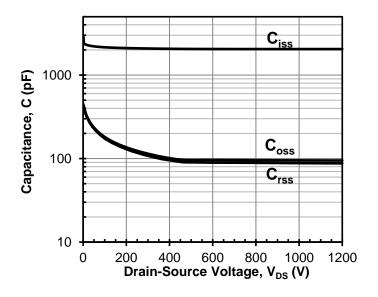


Figure 5 Typical capacitances at 100kHz and $V_{GS} = -20V$

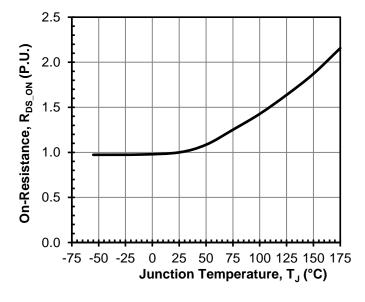


Figure 7 Normalized on-resistance vs. temperature at $V_{GS} = 0V$ and $I_D = 20A$

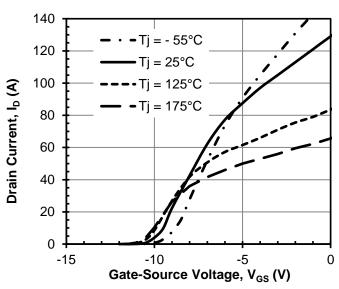


Figure 6 Typical transfer characteristics at $V_{DS} = 5V$

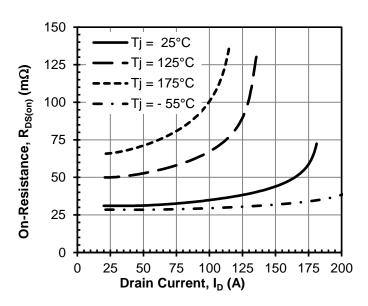


Figure 8 Typical drain-source on-resistance at $V_{GS} = 0V$



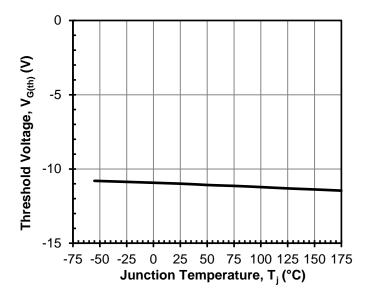


Figure 9 Threshold voltage vs. Tj at $V_{DS} = 5V$ and $I_D = 70mA$

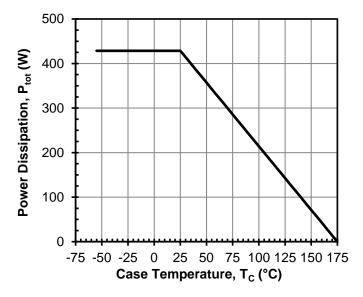


Figure 11 Total power Dissipation

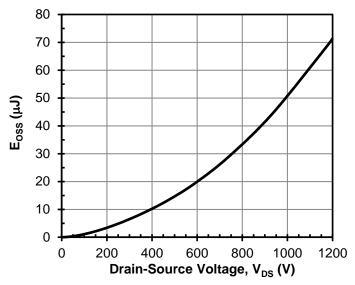


Figure 10 Typical stored energy in C_{OSS} at $V_{GS} = -20V$

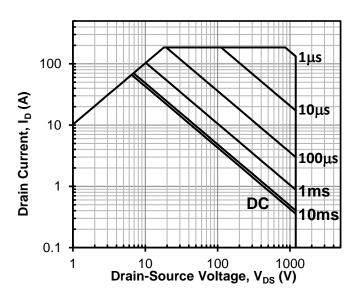


Figure 12 Safe operation area $T_c = 25$ °C, Parameter t_p



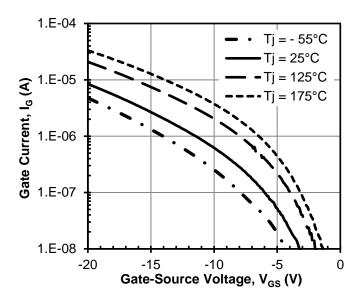


Figure 13 Typical gate leakage current at $V_{DS} = 0V$

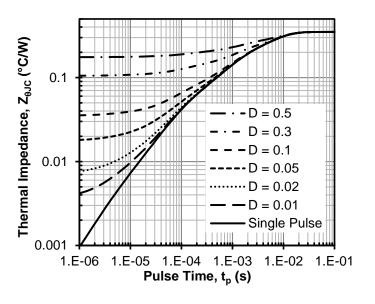


Figure 15 Maximum transient thermal impedance

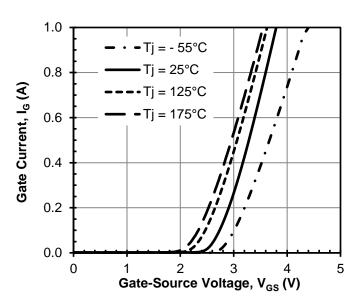


Figure 14 Typical gate forward current at $V_{DS} = 0V$

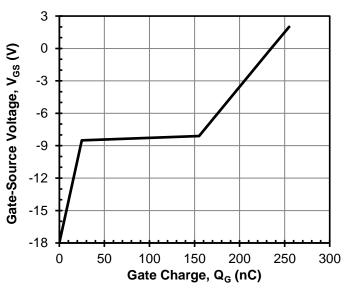
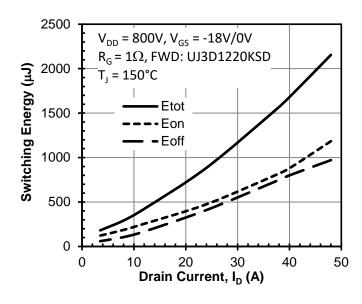


Figure 16 Typical gate charge at $V_{DS} = 800V$ and $I_D = 40A$





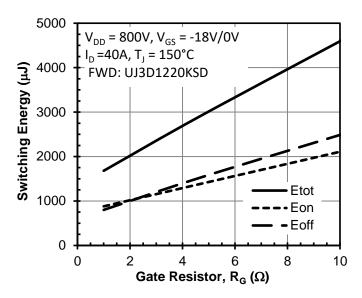


Figure 17 Clamped inductive switching energy vs. drain current at $T_J = 150$ °C

Figure 18 Clamped inductive switching energy vs. gate resistor R_G

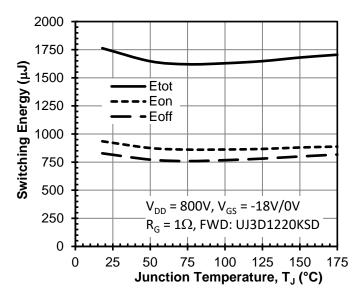


Figure 19 Clamped inductive switching energy vs. junction temperature at $I_D = 40A$

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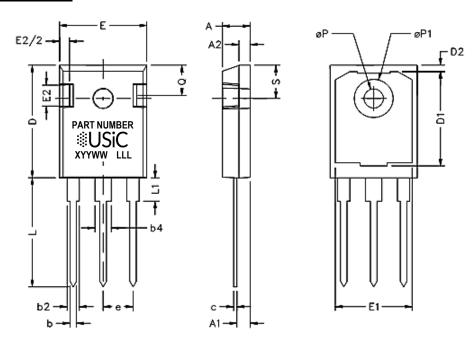
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TO-247-3L PACKAGE OUTLINE, PART MARKING AND TUBE SPECIFICATIONS

PACKAGE OUTLINE

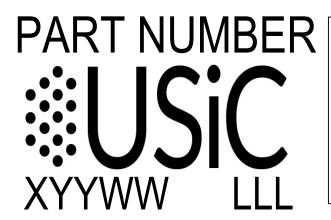


SYM	INC	HES	MILLIMETERS		
	MIN	MAX	MIN	MAX	
А	0.185	0.209	4.699	5.309	
A1	0.087	0.102	2.21	2.61	
A2	0.059	0.098	1.499	2.489	
b	0.039	0.055	0.991	1.397	
b2	0.065	0.094	1.651	2.388	
b4	0.102	0.135	2.591	3.429	
С	0.015	0.035	0.381	0.889	
D	0.819	0.845	20.803	21.463	
D1	0.515	-	13.081	-	
D2	0.02	0.053	0.508	1.346	
E	0.61	0.64	15.494	16.256	
е	0.214	4 BSC	5.44	BSC	
E1	0.53	-	13.462	-	
E2	0.135	0.157	3.429	3.988	
L	0.78	0.8	19.812	20.32	
L1	ı	0.177	ī	4.496	
ØΡ	0.14	0.144	3.556	3.658	
ØP1	0.278	0.291	7.061	7.391	
Q	0.212	0.244	5.385	6.198	
S	0.243	43 BSC 6.17 BSC			



TO-247-3L PACKAGE OUTLINE, PART MARKING AND TUBE SPECIFICATIONS

PART MARKING



PART NUMBER = REFER TO
DS PN DECODER FOR DETAILS

X = ASSEMBLY SITE

YY = YEAR

WW = WORK WEEK

LLL = LOT ID

PACKING TYPE

ANTI-STATIC TUBE

QUANTITY /TUBE: 30 UNITS

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